

## Descriptions

The RLCS3357 is a single SPDT low on-resistance analog switch. It can operate from a single 1.5V to 5.5V power supply. The device offers low ON-state resistance and excellent ON-state resistance matching with break-before-make feature, to prevent signal distortion during the transferring of a signal from one channel to another. The device is capable of truly isolation. Even when A overrides VCC, very little current will flow back to the supply.

## Features

- Low On-resistance,  $R_{on}=1.5\Omega$  when  $A=5V$
- 1.8V Logic Compatible Control Pin
- A Overrides VCC to Achieve True Isolation Even When Supply Is Dead
- High Off-Isolation: -100dB @ 100KHz
- Low Channel-to-Channel Crosstalk: -97dB @ 100KHz
- High Bandwidth ( -3dB @700MHz) Suitable For USB2.0 High-Speed Routing
- Low Quiescent Current (<2uA) With Very Wide Supply Range (1.5V ~ 5.5V)
- DFN1109-6L Package

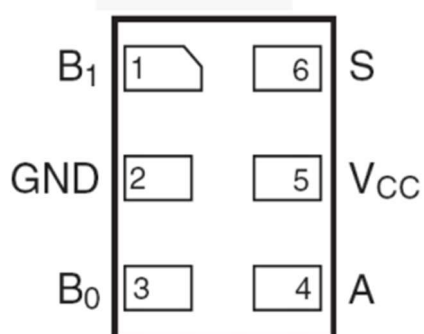
## Applications

- Audio
- Video
- UART,
- USB2.0 Signal and Supply Routing
- Cell phones
- TWS headset

## Order Information

Package		Part Number	Quantity per Reel
DFN1109-6L	Tape and Reel	RLCS3357DN6/R6	3000PCS

## Pin Configuration



## Functions and Pin Configuration

Pin Number	Symbol	Descriptions
1	B <sub>1</sub>	Analog/Digital Signal Port (Normally open)
2	GND	Ground
3	B <sub>0</sub>	Analog/Digital Signal Port (Normally closed)
4	A	Common Signal Port
5	V <sub>CC</sub>	Single Power Supply
6	S	Logic Input Control

## Function Descriptions

Logic Input	Function
S=0	B <sub>0</sub> =A
S=1	B <sub>1</sub> =A

## Absolute Maximum Ratings <sup>(1)</sup>

Parameter	Symbol	Value	Unit
Supply Voltage	V <sub>CC</sub>	-0.3 ~ 6.5	V
Control Input Voltage	V <sub>S</sub>	-0.3 ~ 6.5	V
Continuous Current Through A, B0, B1		±100	mA
Peak Current Through A, B0, B1 (pulsed at 1ms 50% duty cycle)		±200	mA
Storage Temperature Range	T <sub>STG</sub>	-55 ~ 150	°C
Junction Temperature under Bias	T <sub>J</sub>	150	°C
Lead Temperature (Soldering, 10 seconds)	T <sub>L</sub>	260	°C
Thermal resistance	R <sub>θJA</sub>	350	°C/W

## Recommend operating ratings <sup>(2)</sup>

Parameter	Symbol	Value	Unit
Supply Voltage Operating	V <sub>CC</sub>	1.5 ~ 5.5	V
Control Input Voltage	V <sub>S</sub>	-0.3 ~ 5.5	V
Input Signal Voltage	V <sub>A</sub>	-0.3 ~ 5.5	V
Operating Temperature	T <sub>A</sub>	-40 ~ 85	°C

### Note:

1. “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions beyond those indicated in the operational sections of this specification is not implied.

## DC Electronics Characteristics (Ta=25°C, VCC=3.3V, unless otherwise noted)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Input logic high level	V <sub>IH</sub>	VCC: 3.3 ~ 5.5V	1.6			V
		VCC: 1.5 ~ 3.3V	1.4			V
Input logic low level	V <sub>IL</sub>	VCC: 3.3 ~ 5.5V			0.6	V
		VCC: 1.5 ~ 3.3V			0.4	V
Supply quiescent current	I <sub>CC</sub>	I <sub>A</sub> =0, V <sub>S</sub> =0 or V <sub>S</sub> =VCC			1.0	uA
Increase in I <sub>CC</sub> per input	I <sub>CCT</sub>	I <sub>A</sub> =0, VCC=4.5V V <sub>S</sub> >1.8 or V <sub>S</sub> <0.5			1.0	uA
Off state leakage from A to B0 (or B1)	I <sub>A</sub>	V <sub>A</sub> = 5.5V , V <sub>B0(or B1)</sub> = 0V			±2.0	uA
On-Resistance	R <sub>ON1</sub>	V <sub>A</sub> =0 ~ 0.5V, I <sub>A</sub> =30mA		3.0	3.5	Ω
	R <sub>ON2</sub>	V <sub>A</sub> =0.5 ~ 2.0V, I <sub>A</sub> =30mA		3.6	3.9	Ω
	R <sub>ON3</sub>	V <sub>A</sub> =2.0 ~ 4.0V, I <sub>A</sub> =30mA		2.5	3.5	Ω
	R <sub>ON4</sub>	V <sub>A</sub> =4.0 ~ 5.5V, I <sub>A</sub> =30mA		1.5	1.8	Ω
On-Resistance Flatness	R <sub>FLAT1</sub>	V <sub>A</sub> =0 ~ 0.5V, I <sub>A</sub> =30mA		0.7		Ω
	R <sub>FLAT2</sub>	V <sub>A</sub> =0.5 ~ 2.0V, I <sub>A</sub> =30mA		0.5		Ω
	R <sub>FLAT3</sub>	V <sub>A</sub> =2.0 ~ 4.0V, I <sub>A</sub> =30mA		1.6		Ω
	R <sub>FLAT4</sub>	V <sub>A</sub> =4.0 ~ 5.5V, I <sub>A</sub> =30mA		0.3		Ω
On-Resistance Matching Between Channels	Δ R <sub>ON</sub>	V <sub>A</sub> =0~5.5V, I <sub>A</sub> =30mA,		0.1	0.2	Ω

## AC Electronics Characteristics (Ta=25°C, VCC=3.3V, unless otherwise noted)

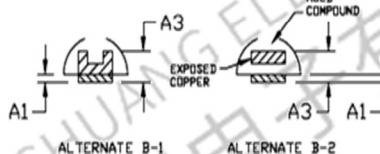
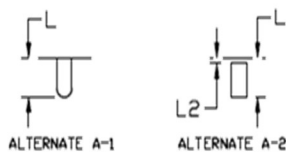
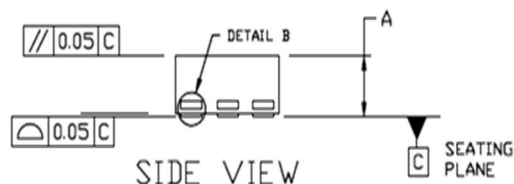
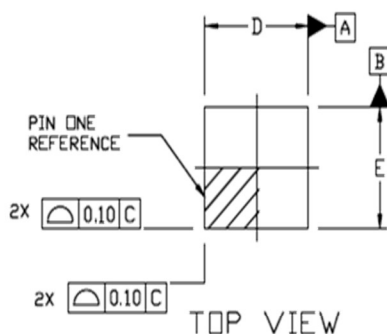
Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Turn-On Time	T <sub>ON</sub>	V <sub>A</sub> =1.5V, C <sub>L</sub> =35pF, R <sub>L</sub> =50Ω		200		ns
Turn-Off Time	T <sub>OFF</sub>	V <sub>A</sub> =1.5V, C <sub>L</sub> =35pF, R <sub>L</sub> =50Ω		200		ns
Break-Before-Make time	T <sub>BBM</sub>	V <sub>A</sub> =1.5V, C <sub>L</sub> =35pF, R <sub>L</sub> =50Ω		500		ns
-3dB Bandwidth	BW	R <sub>L</sub> =50Ω, C <sub>L</sub> =0pF		700		MHz
Off isolation	OIRR	F=1KHz, R <sub>L</sub> =50Ω		-81		dB
		F=10KHz, R <sub>L</sub> =50Ω		-80		dB
Crosstalk	Xtalk	F=1KHz, R <sub>L</sub> =50Ω		-83		dB
		F=10KHz, R <sub>L</sub> =50Ω		-82		dB
Total Harmonic Distortion	THD	F=20Hz to 20KHz V <sub>A</sub> =600mVp-p @ R <sub>L</sub> =32Ω,		-80		dB

## Capacitance (Ta=25°C unless otherwise noted)

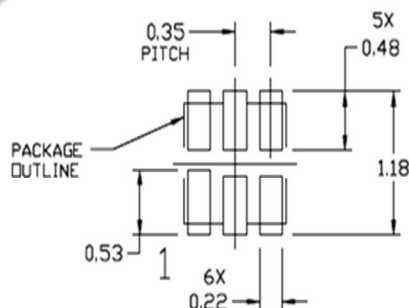
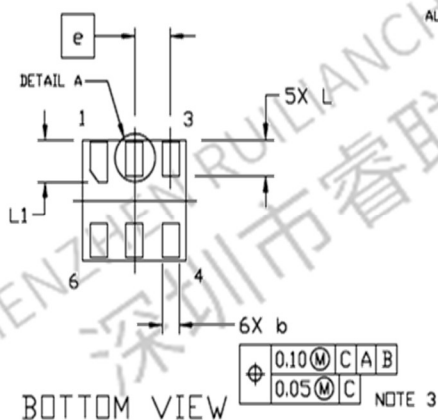
Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Off capacitance	C <sub>OFF</sub>	F=100KHz, VCC=3.3		5		pF
On capacitance	C <sub>ON</sub>	F=100KHz, VCC=3.3		7		pF

**Package Outline Dimensions**

**DFN 1.1x0.9-6L**



DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.45	0.50	0.55
A1	0.00	0.025	0.05
A3	0.13 REF		
b	0.12	0.17	0.22
D	0.90	1.00	1.10
E	0.90	1.00	1.10
e	0.35 BSC		
L	0.25	0.30	0.35
L1	0.30	0.35	0.40
L2	---	---	0.10



**RECOMMENDED MOUNTING FOOTPRINT\***

\* For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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